| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 26 | reinforcement NEAR means | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 11:59 |
| 2 | 2755 | reinforcement NEAR (beam means strip$1) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 12:11 |
| 3 | 1 | (reinforcement NEAR (beam means strip$1)) and (array$2 NEAR waveguide NEAR grating) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 12:02 |
| 4 | 204 | (reinforcement NEAR (beam means strip$1)) and ((array$2 NEAR waveguide NEAR grating) chip die) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 12:02 |
| 5 | 2 | ((reinforcement NEAR (beam means strip$1)) and ((array$2 NEAR waveguide NEAR grating) chip die)) and (copper NEAR plate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 12:10 |
| 6 | 2 | (reinforcement NEAR (beam means strip$1)) and (copper NEAR plate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:08 |
| 7 | 0 | (reinforcement NEAR (beam means strip$1)) same (copper NEAR plate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 12:11 |
| 8 | 8 | (reinforcement NEAR (beam means strip$1)) same copper | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 12:59 |
| 9 | 17 | (reinforcement NEAR (beam means strip$1)) with (chip die) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:07 |
| 10 | 2183 | reinforcement with (chip die) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:08 |
| 11 | 13 | (reinforcement with (chip die) ) and (copper NEAR plate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:08 |

| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 12 | 177 | reinforcement with mount$3 with (chip die) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:18 |
| 13 | 6 | (reinforcement with mount$3 with (chip die) ) and (copper NEAR plate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:19 |
| 14 | 26 | reinforcement with mount$3 with ((part portion) NEAR5 (chip die)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:33 |
| 15 | 1 | (reinforcement with mount$3 with ((part portion) NEAR5 (chip die)) ) and (copper NEAR plate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:35 |
| 16 | 2 | (reinforcement with mount$3 with ((part portion) NEAR5 (chip die)) ) and copper | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:19 |
| 17 | 7 | 5440171.URPN. | USPAT | 2003/03/14 13:21 |
| 18 | 2 | ("4038488" | "5028986").PN. | USPAT | 2003/03/14 13:21 |
| 19 | 1286 | (reinforcement copper metal) with mount$3 with ((part portion) NEAR5 (chip die)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:34 |
| 21 | 51 | ((reinforcement copper metal) with mount$3 with ((part portion) NEAR5 (chip die)) ) and (copper NEAR plate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:35 |
| 20 | 129 | ((copper metal) NEAR plate) with mount$3 with ((part portion) NEAR5 (chip die)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:42 |
| 22 | 11 | (copper NEAR plate) with mount$3 with ((part portion) NEAR5 (chip die)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 13:43 |

| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 6717 | (first NEAR (chip die)) same (second NEAR (chip die)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 16:53 |
| 2 | 1046 | (first NEAR (chip die)) same (second NEAR (chip die)) same (bond$3 combin$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 16:56 |
| 3 | 1079 | (first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 16:57 |
| 4 | 170 | ((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (concave hollow$ curv$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:20 |
| 5 | 91 | (((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (concave hollow$ curv$3)) and (cut$4 dic$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:19 |
| 6 | 469 | ((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (cut$4 dic$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:10 |
| 7 | 245 | (((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (cut$4 dic$3)) and adhesive | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:11 |
| 8 | 1 | ((((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (cut$4 dic$3)) and adhesive) and (purity NEAR level) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:25 |
| 9 | 1 | ((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (purity NEAR level) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:19 |
| 10 | 245 | ((((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (cut$4 dic$3)) and adhesive) and (cut$4 dic$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:19 |
| 11 | 35 | (((((first NEAR (chip die wafer)) WITH (second NEAR (chip die wafer)) WITH (bond$3 combin$3)) and (cut$4 dic$3)) and adhesive) and (cut$4 dic$3)) and (concave curv$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:20 |
| 12 | 4122 | (purity NEAR level) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:25 |

| 13 | 1101 | ( (purity NEAR level)) and (Si silicon) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:25 |
|---|---|---|---|---|
| 14 | 104 | (silicon Si) WITH (purity NEAR level) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:36 |
| 15 | 40 | ( (silicon Si) WITH (purity NEAR level) ) and wafer$1 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:26 |
| 16 | 1 | ((first second) NEAR wafer$1) and (silicon Si) WITH (purity NEAR level) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:32 |
| 17 | 0 | ((first second) NEAR wafer$1) WITH (silicon Si) WITH (purity NEAR level) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:33 |
| 18 | 12382 | ((first second) NEAR wafer$1) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:37 |
| 19 | 9 | ( ((first second) NEAR wafer$1) ) and ((silicon Si) same (purity NEAR level)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:35 |
| 20 | 1 | ( ((first second) NEAR wafer$1) ) and ((silicon Si) WITH (purity NEAR level)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:35 |
| 21 | 213 | (silicon Si) same (purity NEAR level) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:36 |
| 22 | 9 | ( (silicon Si) same (purity NEAR level) ) and ( ((first second) NEAR wafer$1) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:39 |
| 23 | 2080 | (first NEAR wafer$1) WITH (second NEAR wafer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:55 |
| 24 | 3 | ( (first NEAR wafer$1) WITH (second NEAR wafer) ) and ( (silicon Si) same (purity NEAR level) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:38 |
| 25 | 76 | ( (silicon Si) same (purity NEAR level) ) and wafer$1 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 17:39 |

| 26 | 18 | ((first NEAR chip) WITH (second NEAR chip)) and ((first NEAR wafer) WITH (second NEAR wafer)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 18:04 |
| 27 | 9 | ((first NEAR chip) WITH (second NEAR chip)) same ((first NEAR wafer) WITH (second NEAR wafer)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 18:04 |

| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 1642 | 257/620,622.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 08:48 |
| 2 | 744 | 257/620,622.ccls. and (chip die wafer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 08:49 |
| 3 | 127 | (257/620,622.ccls. and (chip die wafer)) and (concave hollow$2 curv$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 09:55 |
| 4 | 377 | (257/620,622.ccls. and (chip die wafer)) and (dic$3 cut$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 09:56 |
| 5 | 244 | ((257/620,622.ccls. and (chip die wafer)) and (dic$3 cut$4)) and (arrang$5 lay-out configur$5) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 09:56 |
| 6 | 135 | (((257/620,622.ccls. and (chip die wafer)) and (dic$3 cut$4)) and (arrang$5 lay-out configur$5)) and shape | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 09:55 |
| 7 | 0 | 6521513.URPN. | USPAT | 2003/03/14 09:19 |
| 8 | 12 | ("4925808" \| "4984358" \| "5501893" \| "5656547" \| "5668400" \| "5753959" \| "5814885" \| "5904546" \| "5910687" \| "5928526" \| "6306731" \| "6387778").PN. | USPAT | 2003/03/14 09:19 |
| 9 | 23 | 5341024.URPN. | USPAT | 2003/03/14 09:46 |
| 10 | 16 | ("4816692" \| "5305222" \| "5341024" \| "5404309" \| "5416722" \| "5450332" \| "5532934" \| "5553273" \| "5581475" \| "5612893" \| "5636131" \| "5663076" \| "5684713" \| "5699260" \| "5822214" \| "5838567").PN. | USPAT | 2003/03/14 09:47 |
| 11 | 1 | 6021267.URPN. | USPAT | 2003/03/14 09:48 |
| 12 | 23 | 5341024.URPN. | USPAT | 2003/03/14 09:49 |
| 13 | 22049 | wafer$1 WITH shape$1 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 09:55 |
| 14 | 6213 | (wafer$1 WITH shape$1) and (concave hollow$2 curv$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:01 |
| 15 | 2882 | ((wafer$1 WITH shape$1) and (concave hollow$2 curv$3)) and (dic$3 cut$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:00 |
| 16 | 2446 | (((wafer$1 WITH shape$1) and (concave hollow$2 curv$3)) and (dic$3 cut$4)) and (arrang$5 lay-out configur$5) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:01 |

| 17 | 323 | ((((wafer$1 WITH shape$1) and (concave hollow$2 curv$3)) and (dic$3 cut$4)) and (arrang$5 lay-out configur$5)) and (substrate NEAR material$1) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:02 |
| 18 | 3 | (((((wafer$1 WITH shape$1) and (concave hollow$2 curv$3)) and (dic$3 cut$4)) and (arrang$5 lay-out configur$5)) and (substrate NEAR material$1)) and (waveguide NEAR grating) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:02 |
| 19 | 26418 | wafer$1 WITH (dic$3 cut$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:00 |
| 20 | 510 | (wafer$1 WITH (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape$1) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:01 |
| 21 | 430 | ((wafer$1 WITH (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape$1)) and (arrang$5 lay-out configur$5) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:01 |
| 23 | 1 | ((((wafer$1 WITH (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape$1)) and (arrang$5 lay-out configur$5)) and (substrate NEAR material$1)) and (waveguide NEAR grating) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:02 |
| 22 | 86 | (((wafer$1 WITH (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape$1)) and (arrang$5 lay-out configur$5)) and (substrate NEAR material$1) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/14 10:03 |
| 24 | 0 | 6193585.URPN. | USPAT | 2003/03/14 10:16 |
| 25 | 18 | ("4836881" \| "4863529" \| "5071785" \| "5240749" \| "5241140" \| "5270028" \| "5270077" \| "5273731" \| "5294381" \| "5382809" \| "5584045" \| "5587013" \| "5736226" \| "5776246" \| "5855998" \| "5874130" \| "5964942" \| "6051063").PN. | USPAT | 2003/03/14 10:16 |